

In The Claims

Previously presented claims are as follows:

1. (Previously presented) An etching agent for etching copper in an etching process comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of 10.01% to about 23.31% by weight of the etching agent, said etching agent etching the copper at an approximately uniform rate throughout the etching process.

2. (Original) An etching agent for copper according to Claim 1, wherein said aqueous solution contains acetic acid.

Claims 3-16 (Cancelled)

17. (Previously presented) An etching agent according to claim 1, wherein said etching agent is capable of selectively etching the copper.